# CATIROC

## Production Plan

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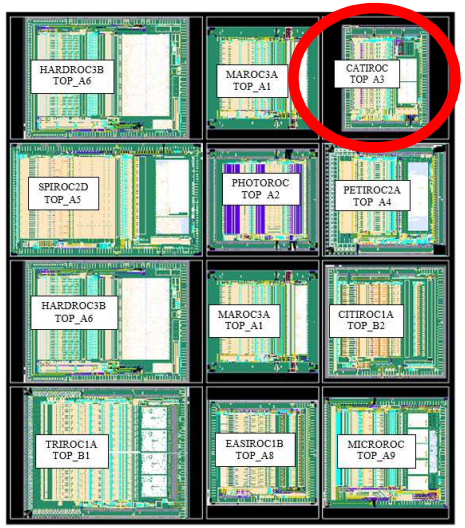
Organization for Micro-Electronics desiGn and Applications

# CATIROC production

CATIROC:

- Process: **AMS 0.35 µm SIGe**
- Die dimensions: 3.3 mm x 4 mm (13.2 mm²)
- Packaging: **TQFP208**




→ **Option1:** Refabricate reticle 2015

- → But only 60 chips/wafer
- → Unfortunately no request for the other chips
- → To produce 24-30 wafers → 1400-1800 CATIROC

→ **Option2:** Make new reticle

- → New masks with only CATIROC = 720 chips/wafer
- → 6 wafers produced (min)
- → 4500 CATIROC

→ **Option3:** Make shared new reticle

- → New masks with CATIROC + CITIROC2
- → 3 wafers for CATIROC and 3 wafers for CITIROC2
- → Could also apply to option 1 if we find other customer

# Production schedule

FOR ~ 2000 ASIC CATIROC